



2823

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re the Application of: Bojkov, et al.

Conf. No.: 8827

Docket No.: TI-33474

Serial No.: 09/963,493

Examiner: Coleman, W.D.

Filed: 09/27/01

Art Unit: 2823

For: Methods and Apparatus for Manufacturing Ball Grid Array Semiconductor
Device Packages

Amendment under 37 CFR 1.111

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on

August 12, 2003.

Elizabeth Austin

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 05/12/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.